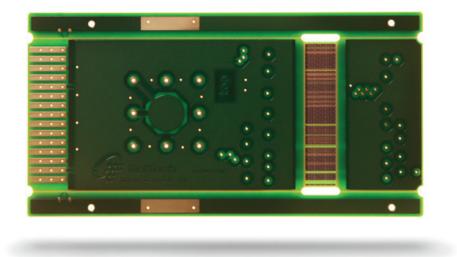




Multilayer HDI RF IMS Flexible Rigid-Flex Semi-Flex Double sided

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## **Semi-Flex**

Semi-flex PCBs use specialized FR-4 materials and a specific manufacturing method to create a flex-to-install design that can provide an economical solution for certain applications.

## SEMI-FLEX PCBs – TECHNICAL SPECIFICATION

FEATURE	NCAB'S TECHNICAL SPECIFICATION
Number of layers	1 - 4 layers, with $1 - 2$ conductive layers in bending area.
Technology highlights	The process uses controlled depth routing of the FR-4 to achieve a flexible / bending section within a traditionally rigid FR-4. Only suitable for static operations – bends typically just for installation. A lower cost solution for some very specific "flex-to-fit" applications.
Bending performance	50 x bend cycles of $0^{\circ} - 90^{\circ} - 0^{\circ}$
Bend features	5mm radius / max bending angle 90°
Materials	FR4 – special for static flex applications
Copper weights (finished)	35um
Minimum track and gap	0.075mm / 0.075mm
PCB thickness	1.00mm – 2.00mm
PCB thickness in flex section	0.25mm ± 0.05mm
Maximum dimensions	538mm x 610mm
Surface finishes available	HASL (SnPb), LF HASL (SnNiCu), OSP, ENIG, Immersion Tin, Immersion Silver, Electrolytic gold, Gold fingers
Minimum mechanical drill	0.20mm